



Eternal Semiconductor Inc.

ET8818

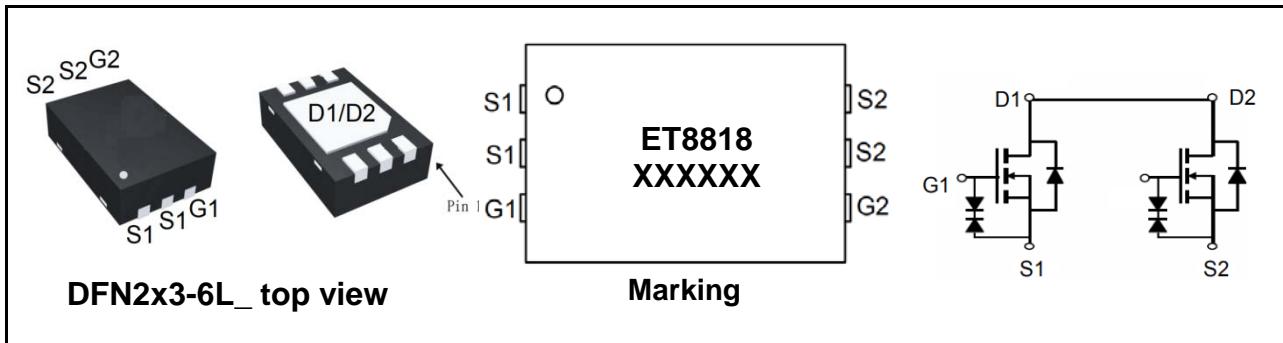
Dual N-Channel Enhancement-Mode MOSFET (20V,10A)

PRODUCT SUMMARY

V_{DSS}	I_D	$R_{DS(on)}$ (mΩ) Typ
20V	10A	7.2 @ $V_{GS} = 4.5V$, $I_D = 10A$
		7.5 @ $V_{GS} = 4.0V$, $I_D = 5A$
		11 @ $V_{GS} = 2.5V$, $I_D = 2.5A$

Features

- Super high density cell design for extremely low RDS(ON)
- Exceptional on-resistance and maximum DC current capability
- ESD Rating:2000V HBM
- Lead (Pb) -free and halogen-free



Absolute Maximum Ratings ($T_A=25^\circ C$, unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current (Continuous)@ $T_A=25^\circ C$	10	A
	Drain Current (Continuous)@ $T_A=75^\circ C$	8	A
I_{DM}	Drain Current (Pulsed) ^a	32	A
P_D	Total Power Dissipation @ $T_A=25^\circ C$	1.5	W
	Total Power Dissipation @ $T_A=75^\circ C$	1.2	W
T_j, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150	°C
R_{QJA}	Thermal Resistance Junction to Ambient (PCB mounted) ^b	80	°C/W

a: Repetitive Rating: Pulse width limited by the maximum junction temperature.

b: 1-in² 2oz Cu PCB board



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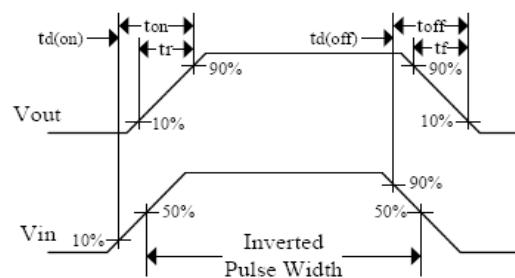
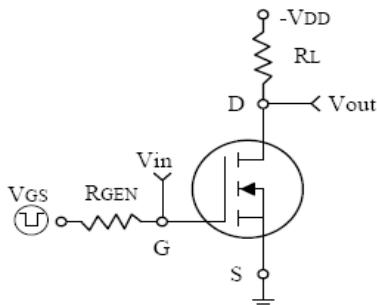
Electrical Characteristics ($T_A=25^\circ C$, unless otherwise noted)

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
• Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
• On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.7	1.0	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=4.5V, I_D=10A$	6	7.2	8.9	$m\Omega$
		$V_{GS}=4.0V, I_D=5A$	6.3	7.5	9.2	
		$V_{GS}=2.5V, I_D=2.5A$	10.3	11	12.5	
g_{FS}	Forward Transconductance	$V_{DS}=10V, I_D=5A$	5	-	-	s
• Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, f=1MHz$	-	1265	-	PF
C_{oss}	Output Capacitance		-	225	-	
C_{rss}	Reverse Transfer Capacitance		-	155	-	
• Switching Characteristics						
Q_g	Total Gate Charge	$V_{DS}=15V, I_D=20A, V_{GS}=10V$	-	29	-	nC
Q_{gs}	Gate-Source Charge		-	5.2	-	
Q_{gd}	Gate-Drain Charge		-	6.3	-	
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=15\Omega, I_D=20A, V_{GEN}=10V, RG=6\Omega$	-	300	-	nS
t_r	Turn-on Rise Time		-	1000	-	
$t_{d(off)}$	Turn-off Delay Time		-	4000	-	
t_f	Turn-off Fall Time		-	2500	-	
• Drain-Source Diode Characteristics						
V_{SD}	Drain-Source Diode Forward	$V_{GS}=0V, I_S=10A$	-	0.85	1.2	V

Note: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$



Typical Characteristics Curves (Ta=25°C, unless otherwise note)



Switching Test Circuit and Switching Waveforms

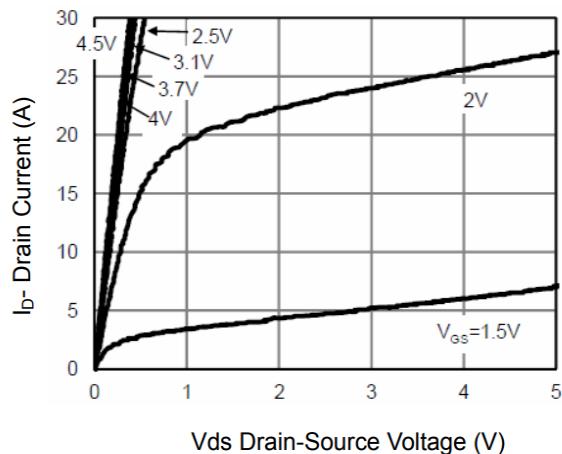


Figure 1 Output Characteristics

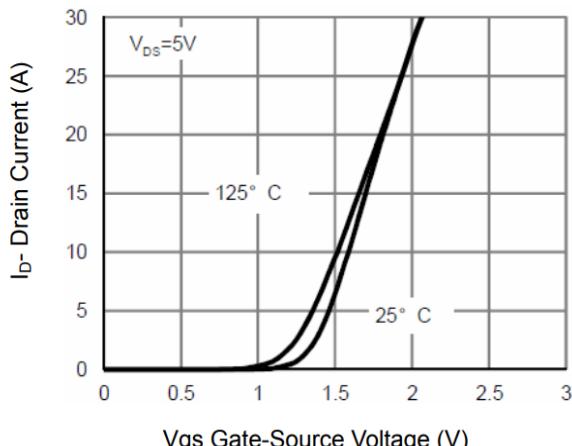


Figure 2 Transfer Characteristics

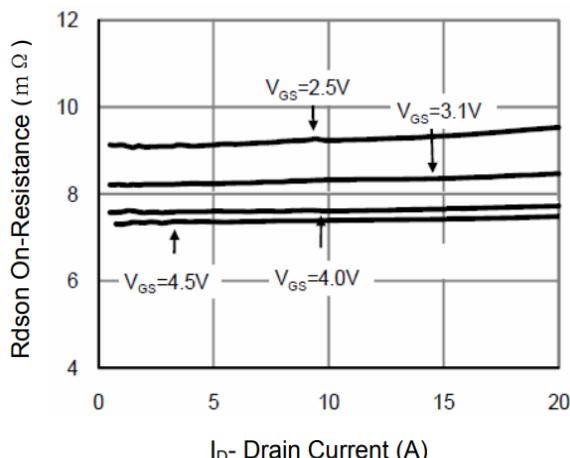


Figure 3 Rdson- Drain Current

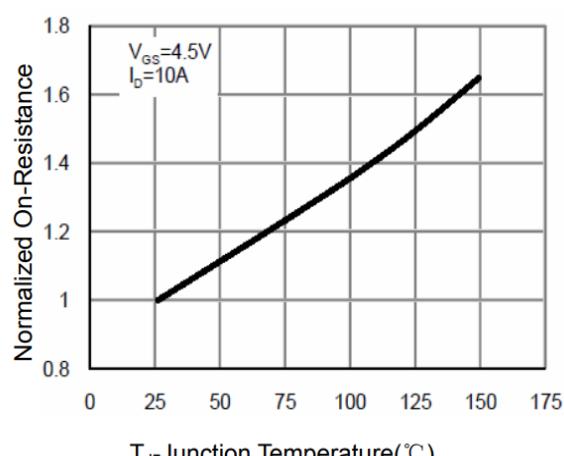


Figure 4 Rdson-Junction Temperature



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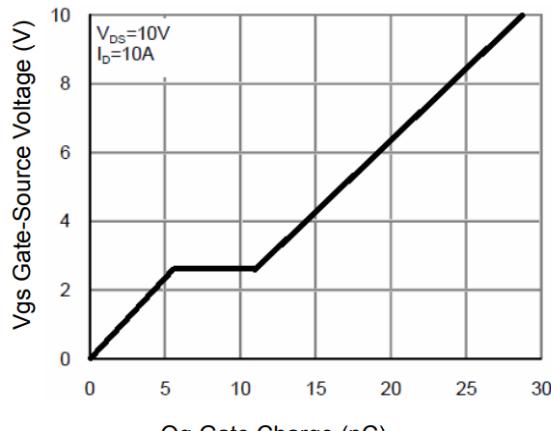


Figure 5 Gate Charge

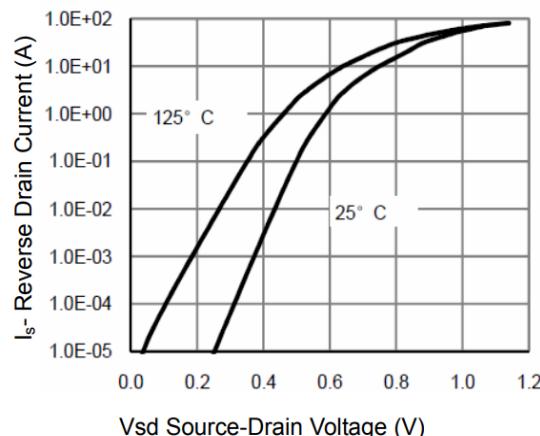


Figure 6 Source-Drain Diode Forward

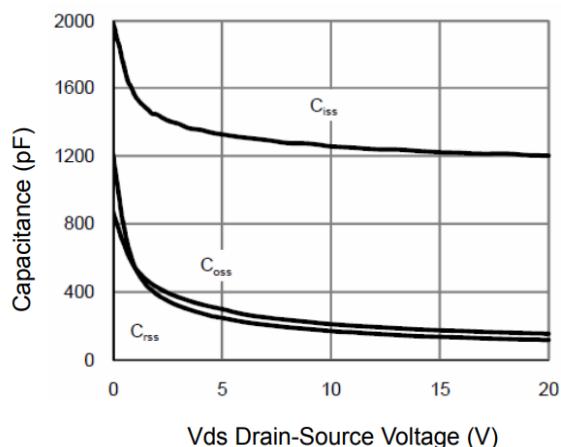


Figure 7 Capacitance vs Vds

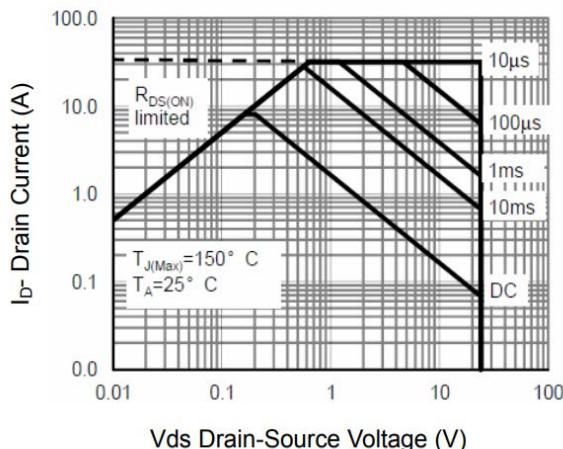


Figure 8 Safe Operation Area

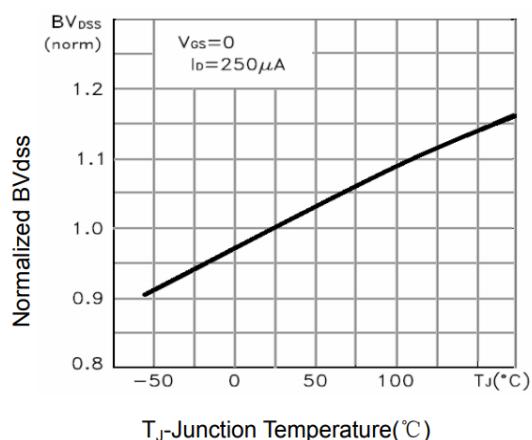


Figure 9 BV_{DSS} vs Junction Temperature

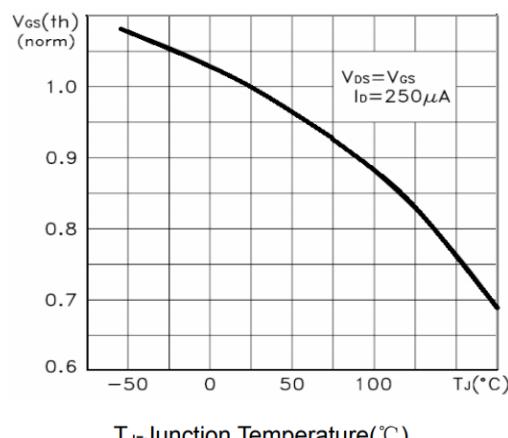


Figure 10 $V_{GS(th)}$ vs Junction Temperature



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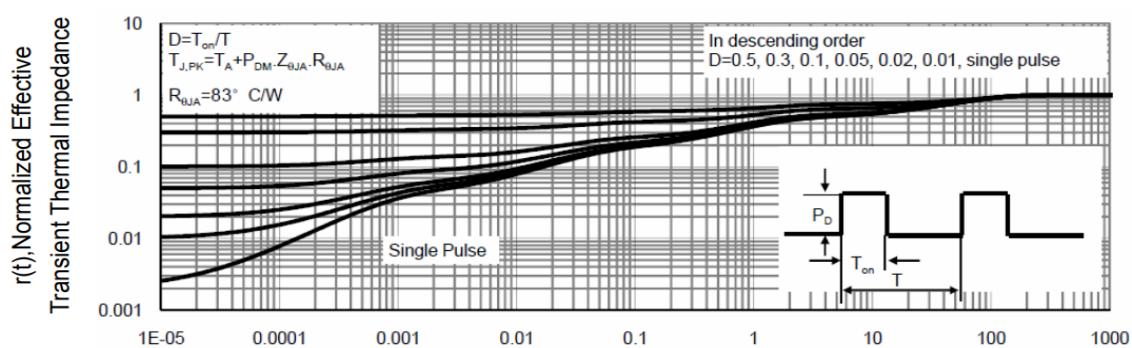
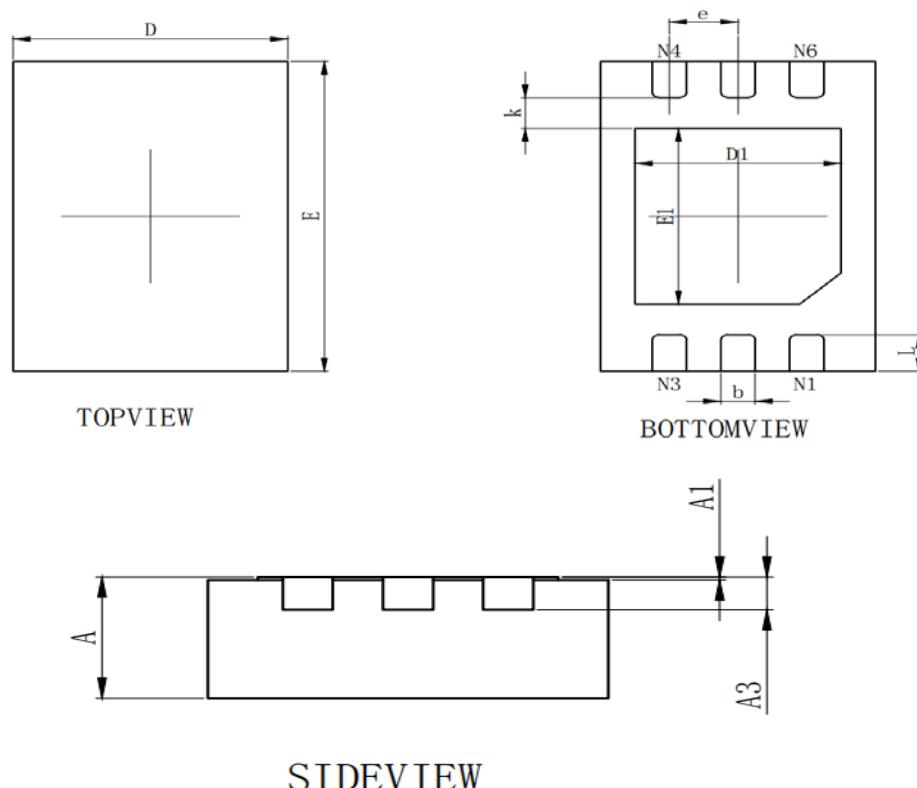


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN2*3-6L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF		0.008REF	
D	1.95	2.050	0.077	0.081
E	2.950	3.050	0.116	0.120
D1	1.450	1.550	0.057	0.061
E1	1.650	1.750	0.065	0.069
k	0.200MIN		0.008MIN	
b	0.200	0.300	0.008	0.012
e	0.500TYP		0.020TYP	
L	0.300	0.400	0.012	0.016